

MacDermid's Professional Development Seminar Series Dynamic Chemistries for Electronics – Vol.1

Date,Time	May 29 (Fri.), 2015 9:00~17:30
Location	Hotel KSP (3-2-1 Sakado, Takatsu-ku, Kawasaki, Kanagawa, Japan) KSP Hall "AKEBONO" (3rd Floor)



Program

* Schedule and titles are tentative and may be revised.

8:30~ 9:00

Registration

9:00~ 9:05



Opening Remarks: Julian Bashore, Managing Director - Japan

9:05~ 9:35



MacDermid Technology Roadmap: Chemicals Make The Connections
Presenter: Joseph D'Ambrisi, Vice President - Electronics Solutions
Interpreter: Tetsuo Takatori

9:35~10:05



Advanced ViaFill Technology for surface copper minimization
Presenter: Jim Watkowski, Director of Metallization Technologies
Interpreter: Yasuhiro Mikami

10:05~10:20

Coffee/Tea Break

10:20~10:50



Copper Filling of Through Holes on Varying Substrate Thickness
Presenter: Jim Watkowski, Director of Metallization Technologies
Interpreter: Yoshihiro Maeda

10:50~11:20



MID
Presenter: Lenora Toscano, Director of OEM Applications
Interpreter: Toshiya Watanabe

11:20~12:05



Introduction of Module Technology for IoT and M2M
Guest Speaker: Dr. Akihiko Happoya, Chief Specialist, System Packaging Technology Group, System & Software Solution Center, Toshiba Corporation

12:05~12:50

Lunch (3rd Floor "Gallery")

12:50~13:35



Printed Circuit Board Market Overview (Tentative)

Guest Speaker: Kaz Hirasaka, Consultant, Prismark Partners LLC

13:35 ~ 14:20



Low Etch Blackhole Technology for High Technology Applications

Presenter: Jim Watkowski, Director of Metallization Technologies
Interpreter: Masaomi Aoki

14:20~15:00



Advancements in Semi Additive Process for IC Substrate Build-up Packages

Presenter: Dr. Fei Peng, Senior Research Chemist
Interpreter: Naomi Ando

15:00~15:10

Coffee/Tea Break

15:10~15:50



The History of Oxide Alternatives - Past & Present. The Future is Here with M-Speed for High Speed Signal Integrity

Presenter: Steve Castaldi, Director - Electronics Specialties
Interpreter: Yasuhiro Mikami

15:50~16:20



OEM Initiative: Increasing Collaboration within the Electronics Supply Chain

Presenter: Lenora Toscano, Director of OEM Applications
Interpreter: Tetsuo Takatori

16:20~17:30

Laboratory Tour

18:00~

Dinner (3rd Floor KSP Hall "HIKARI")

Attendance: Mr. Tad Ericson, Director - ASF Asia, MacDermid, Inc.
Dr. Ernest Long, Director of Research, MacDermid, Inc.
Julian Bashore, Managing Director - Japan
Tohru Takazawa, Manager, ES Sales
Naomi Ando, Manager, ES R&D
Masaomi Aoki, General Manager - MacDermid (Shenzhen) Trading Co., Ltd.
and others